



Process Flow Chart for Multilayer PCB

- 1. Board Cutting**
- 2. Inner layer Dry Film**
- 3. Inner layer Develop, Etch & Strip (DES)**
- 4. AOI**
- 5. Inner layer Brown Oxide**
- 6. Lay-Up**
- 7. Lamination**
- 8. X-Ray Drilling**
- 9. Drilling**
- 10. Desmear, PTH & Panel Plating**
- 11. Outer layer Dry Film**
- 12. Develop, Etch & Strip (DES)**
- 13. Solder Mask**
- 14. Silkscreen**
- 15. Surface treatment (Immersion Gold/HASL-LF)**
- 16. Routing (Profiling)**
- 17. Electrical Test**
- 18. Packing**